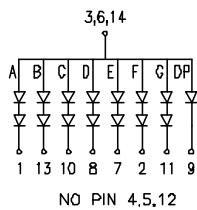
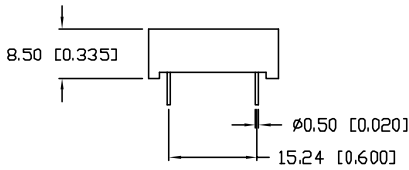
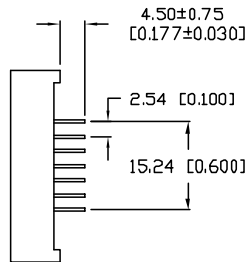
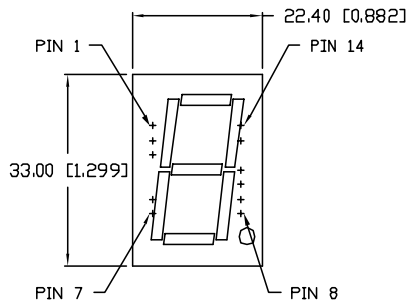


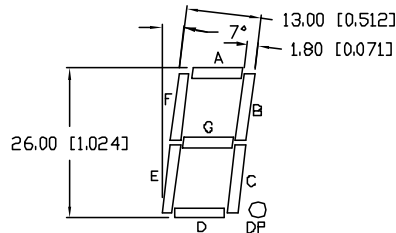
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DIGIT DETAIL



ELECTRO-OPTICAL CHARACTERISTICS $T_A=25^{\circ}\text{C}$ $I_f=10\text{mA}$

| PARAMETER | MIN | TYP | MAX | UNITS | TEST COND |
|-------------------|----------------------|---------|---------|----------------|----------------------|
| PEAK WAVELENGTH | | 660 | | nm | |
| FORWARD VOLTAGE * | | 3.4/1.7 | 4.6/2.3 | V_f | |
| REVERSE VOLTAGE | 4.0 | | | V_r | $I_f=100\mu\text{A}$ |
| AXIAL INTENSITY | | 20000 | | μcd | $I_f=10\text{mA}$ |
| EMITTED COLOR: | RED | | | | |
| FACE COLOR: | GRAY | | | | |
| SEGMENT COLOR: | MILKY WHITE DIFFUSED | | | | |

* SECOND VALUE FOR SINGLE CHIP IN DECIMAL POINT.

LIMITS OF SAFE OPERATION AT 25°C PER CHIP

| PARAMETER | MAX | UNITS |
|--------------------------|------------|------------|
| PEAK FORWARD CURRENT* | 150 | mA |
| STEADY CURRENT | 30 | mA |
| POWER DISSIPATION | 100 | mW |
| DERATE FROM 25°C | -1.2 | mW/°C |
| OPERATING, STORAGE TEMP. | -40 TO +85 | °C |
| SOLDERING TEMP. | +260 | °C |
| 2.0mm FROM BODY | | 3 SEC. MAX |

* $t < 10\mu\text{s}$

*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 [±0.038], XX=±0.5 [±0.020], XXX=±0.25 [±0.010], XXXX=±0.127 [±0.005]. LEAD SIZE=±0.05 [±0.002], LEAD LENGTH=±0.75 [±0.030], NN=DECIMAL PRECISION MAX.=+0.00 DECIMAL PRECISION

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1" SEVEN SEGMENT DISPLAY, 660nm RED,
GREY FRONT, WHITE SEGMENTS, COMMON ANODE.

RELIABILITY NOTE
OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

| | | | |
|-----------------|-------------|--------------|--------------|
| DRAWN BY: CT | CHECKED BY: | APPROVED BY: | DATE: 8.3.01 |
| | | | PAGE: 1 OF 1 |
| | | | SCALE: N/A |